

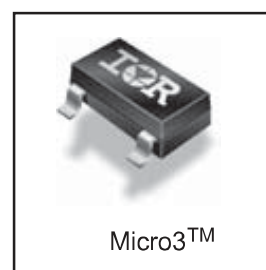
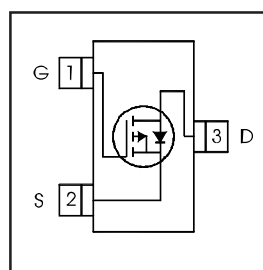
- Ultra Low On-Resistance
- P-Channel MOSFET
- Surface Mount
- Available in Tape & Reel
- Low Gate Charge

V_{DS}	$R_{DS(on)}$ max (m Ω)	I_D
-30V	98@ $V_{GS} = -10V$	-3.0A
	165@ $V_{GS} = -4.5V$	-2.6A

Description

These P-channel MOSFETs from International Rectifier utilize advanced processing techniques to achieve the extremely low on-resistance per silicon area. This benefit provides the designer with an extremely efficient device for use in battery and load management applications.

A thermally enhanced large pad leadframe has been incorporated into the standard SOT-23 package to produce a HEXFET Power MOSFET with the industry's smallest footprint. This package, dubbed the Micro3™, is ideal for applications where printed circuit board space is at a premium. The low profile (<1.1mm) of the Micro3 allows it to fit easily into extremely thin application environments such as portable electronics and PCMCIA cards. The thermal resistance and power dissipation are the best available.



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{DS}	Drain- Source Voltage	-30	V
I_D @ $T_A = 25^\circ C$	Continuous Drain Current, V_{GS} @ -10V	-3.0	A
I_D @ $T_A = 70^\circ C$	Continuous Drain Current, V_{GS} @ -10V	-2.4	
I_{DM}	Pulsed Drain Current ①	-24	
P_D @ $T_A = 25^\circ C$	Power Dissipation	1.25	W
P_D @ $T_A = 70^\circ C$	Power Dissipation	0.80	
	Linear Derating Factor	10	mW/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to + 150	°C

Thermal Resistance

	Parameter	Max.	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient③	100	°C/W